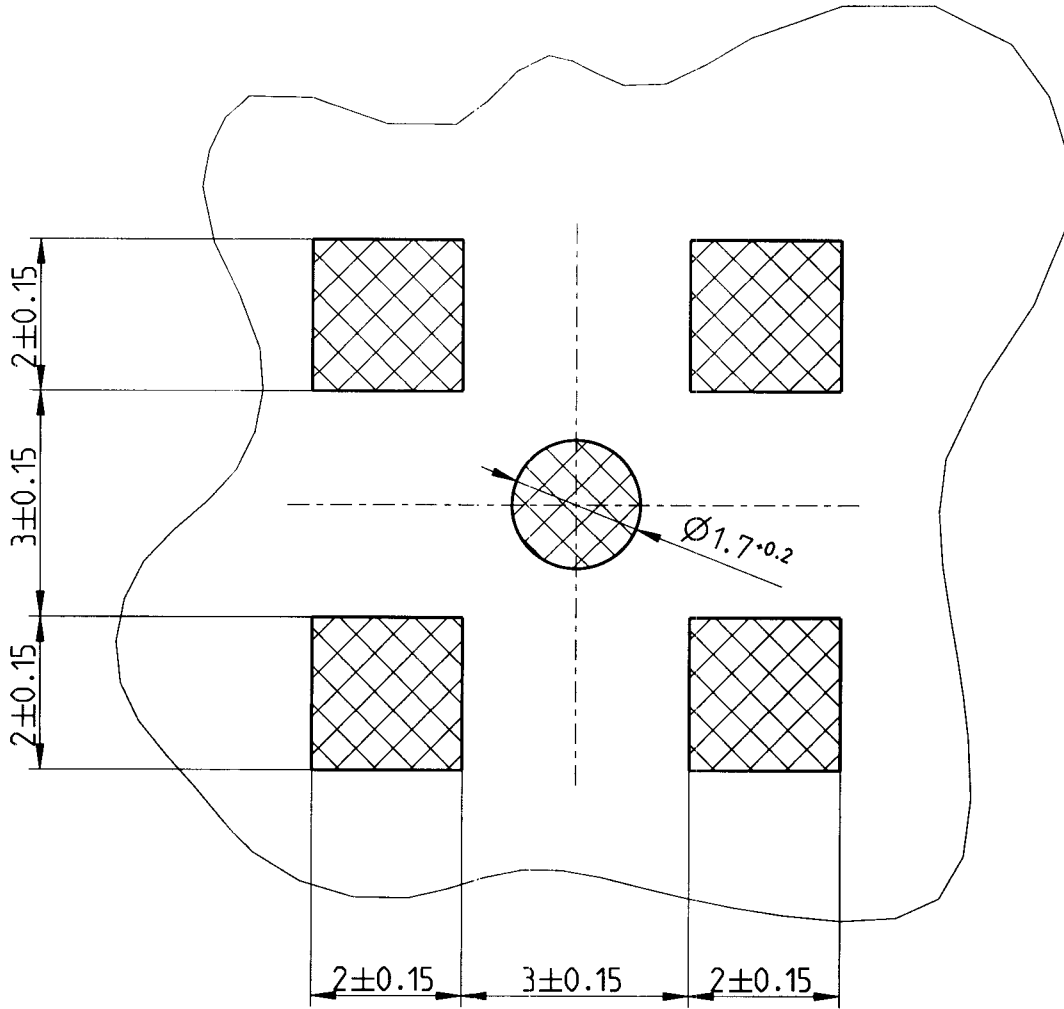


Leiterplatten-Layout
 PCB layout
 B 147



A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.

Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector.

In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

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Formel: TCC_05_PZ-A-Einzeile
 Date: A-LEISTUNG_008.F08
 Version: 1.1

ISO-Projektion
 Methode E

Rosenberger Hochfrequenztechnik 84526 Tittmoning Pro/ENGINEER				general tolerance ISO 2768 RN 006-01 m-H dimensions <0,5 and symmetry		scale: 10:1	weight(g): surface(mm²):.
				material:		title:	
				drawn 12.08.2002 W_Blakborn check 10.5.00 appr.	Leiterplatten-Layout PCB layout		
				dimensioning incl. finish			
b00	06-0194	S_Krautenbac	28.04.2006		drawing-no.: MB_147	sheet: 1	
a00	05-s264	M_Singhammer	18.07.2005			of: 1	
100	03-0009	A_Nobis	22.10.2003	distribu- FE AZ QSM RMT tion to: X	remarks:		
rev.	change-no	name	date				